

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (currently amended) A printed circuit board comprising:

an insulative substrate;

a conductor pattern formed on the substrate; and

a protection film coating the substrate and the conductor pattern, wherein the conductor pattern includes a bottom surface ~~entirely~~ directly contacting the substrate, a top surface opposite to the bottom surface, and a pair of flat angled side surfaces extending from the bottom surface to the top surface, each of the side surfaces having a lower ~~side surface~~ portion covered by the protection film and an upper ~~side surface~~ portion exposed from the protection film, wherein both the bottom surface and the top surface have widths, ~~both~~ the lower portion of each side surface covered by the protection film and the conductor pattern have heights, and wherein the width of the bottom surface is greater than the width of the top surface.

Claim 2 (currently amended) The printed circuit board according to claim 1, wherein the conductor pattern has a trapezoidal cross-section ~~that is perpendicular to the bottom surface of the conductor pattern.~~

Claim 3 (canceled)

Claim 4 (currently amended) The printed circuit board according to claim 1, wherein the height of the lower portion of each side surface covered by the protection film in the conductor pattern is 50% or greater and less than 100% of the height of the conductor pattern.

Claim 5 (currently amended) The printed circuit board according to claim 1, wherein the top surface and the upper portion of the side surfaces are coated by a plating.

Claim 6 (currently amended) The printed circuit board according to claim 5, further comprising a solder ball contacting the ~~conductor pattern~~ plating at the upper portion of the side surfaces.

Claim 7 (previously presented) The printed circuit board according to claim 1, wherein a value X is obtained by the following formula:

$$X = ((c-d) / 2) / p$$

where c is the width of the bottom surface, d is the width of the top surface, and p is the height of the conductor pattern, and wherein X is in the range of 0.1 to 2.5.

Claim 8 (currently amended) A method for fabricating a printed circuit board comprising the steps of:

etching an insulative substrate including a conductor to form a conductor pattern having a bottom surface ~~entirely~~ directly contacting the substrate, a top surface opposite to the bottom surface, and a pair of flat angled side surfaces extending from the bottom surface to the top surface, wherein the conductor pattern is formed so that a width of the bottom surface is greater than a width of the top surface;

applying an insulative protection film to the conductor pattern and the substrate; and
removing ~~part~~ a portion of the protection film to expose the top surface and ~~a part~~ an upper portion of each of the side surfaces.

Claim 9 (currently amended) The fabrication method according to claim 8, further comprising the steps of:

plating the exposed top surface and upper portion of the conductor pattern; and
joining a solder ball to the plated top surface and upper portion of the conductor pattern.